

DE LA RECHERCHE À L'INDUSTRIE



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NANOWIRE BASED FLEXIBLE PIEZOELECTRIC SENSOR

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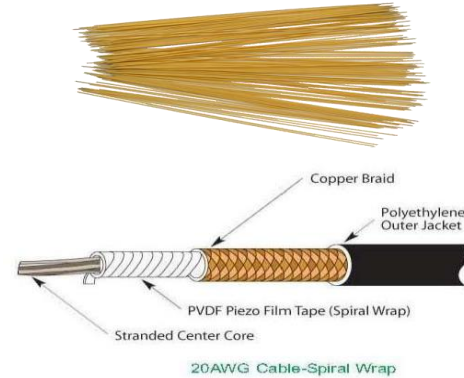
COMSOL
CONFERENCE
2015 GRENOBLE

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What materials for piezoelectricity?

Usual commercial solutions:

- ✓ Ceramics : PZT
- ✓ Polymers
PVDF (polyvinylidene fluoride)



(fragile)

(need ext. Polar.)

Nanowire based solutions :

- ✓ Vertically grown GaN nanowires [1].
- ✓ ZnO nanogenerators [2]

Exploiting intrinsic piezoelectric properties

[1] J. Eymery et al., C.R Physique **14** (2013) 221

[2] Z.L. Wang, *Piezotronics and Piezo-Phototronics*, Microtechnology and MEMS, Springer-Verlag 2012

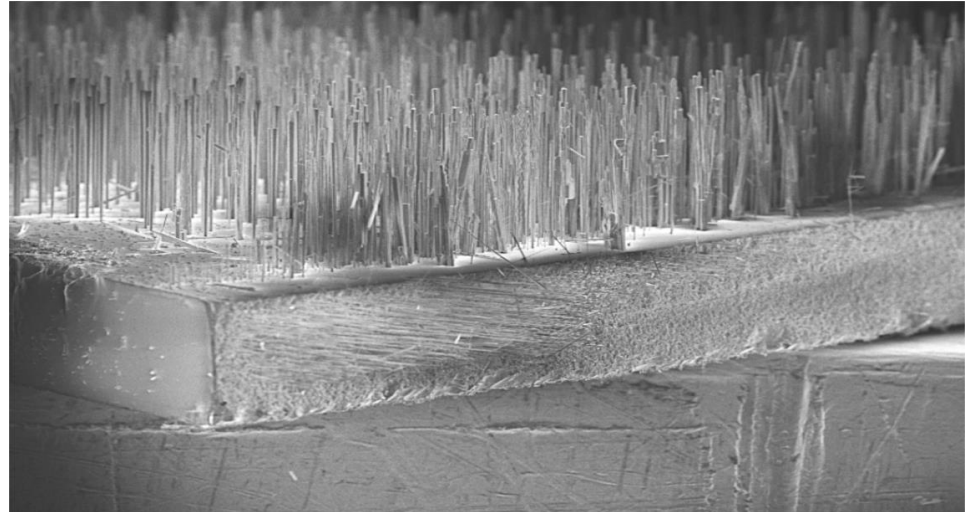
How are the GaN wires fabricated?

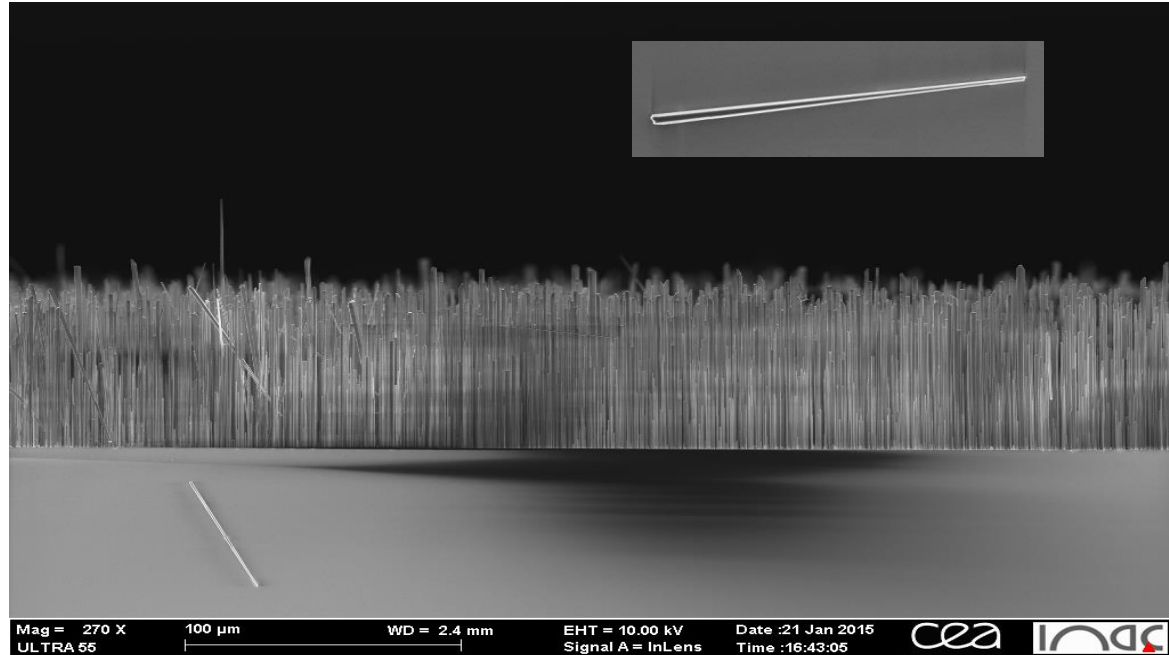
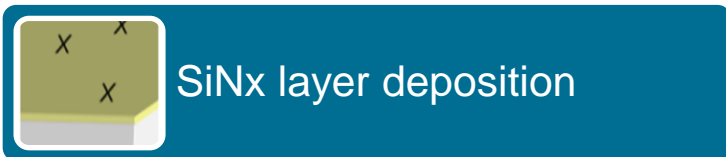
Top-down approach :

- ✓ Lithography and patterning
- ✓ Etching
- ✓ Sacrificial layers

Bottom-up processes :

- ✓ Hybrid vapor phase epitaxy
- ✓ Molecular Beam Epitaxy
- ✓ Metal organic Vapor Phase Deposition



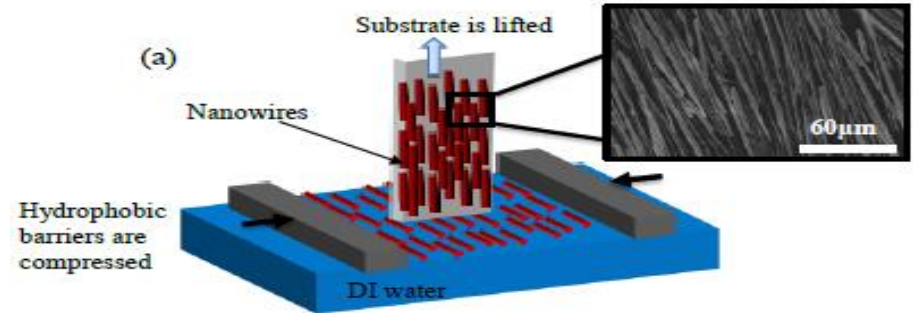


J. Eymery et al., *Compte Rendu Physique* 14 (2013) 221

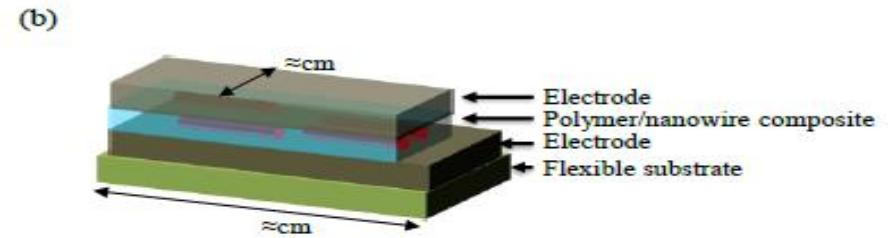
R. Koester et al., *Nanotechnology* 21 (2010) 015602

Assembling the wires and device realization

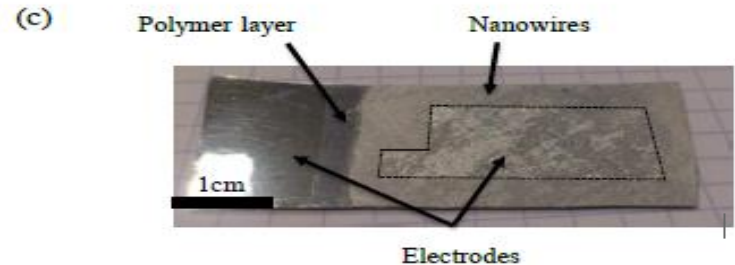
■ Langmuir-Blodgett method



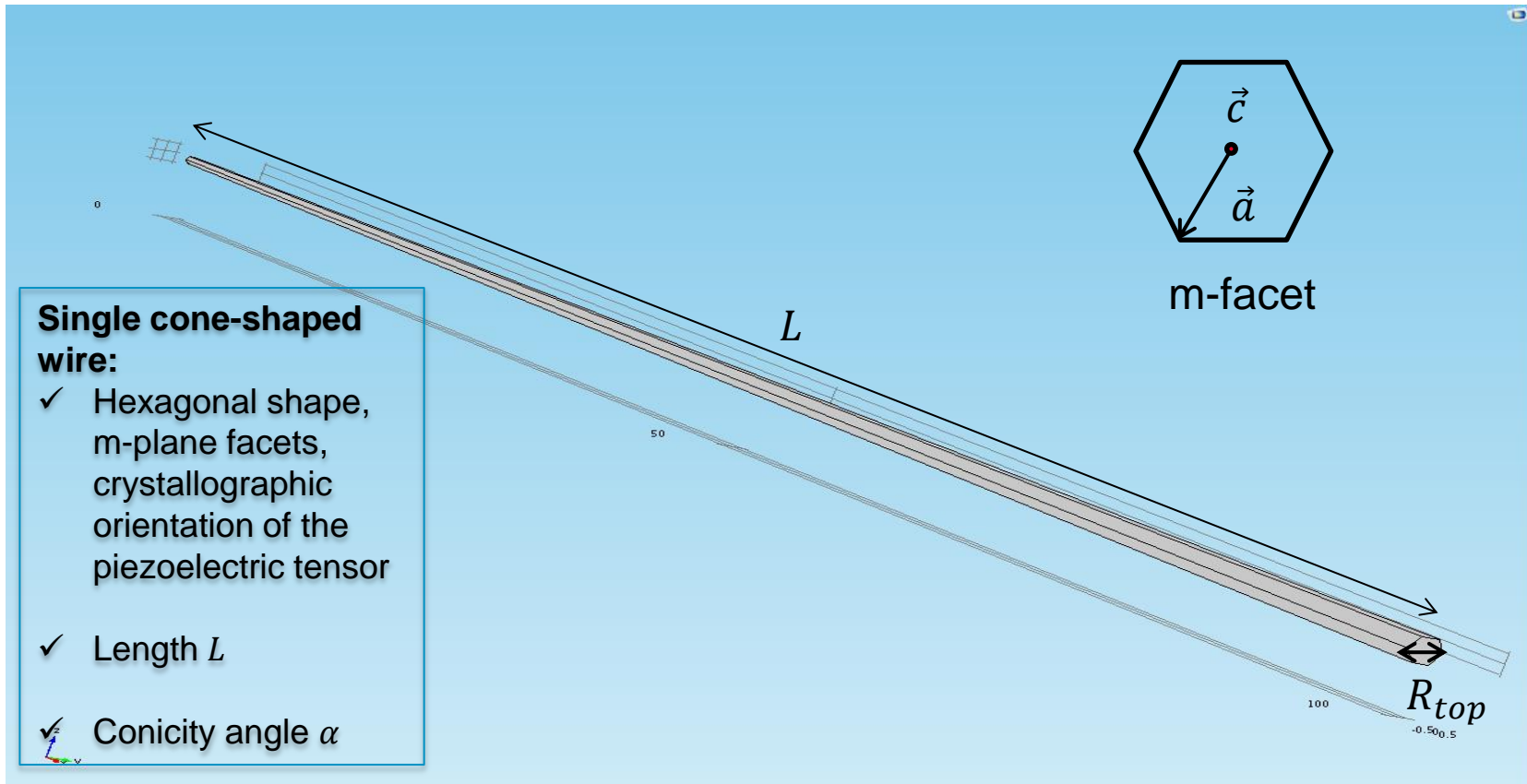
■ Capacitive structure



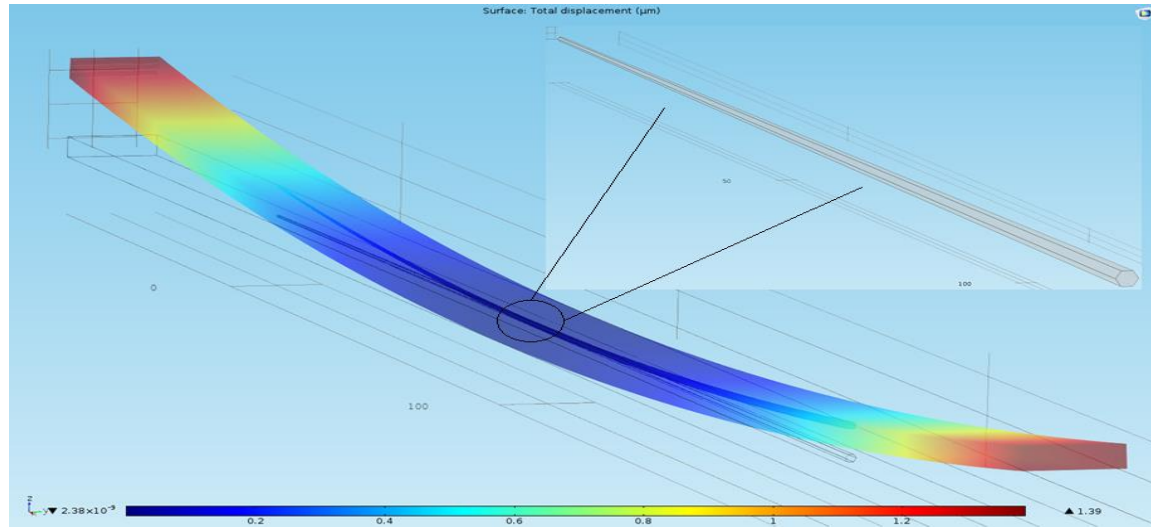
■ Device integration



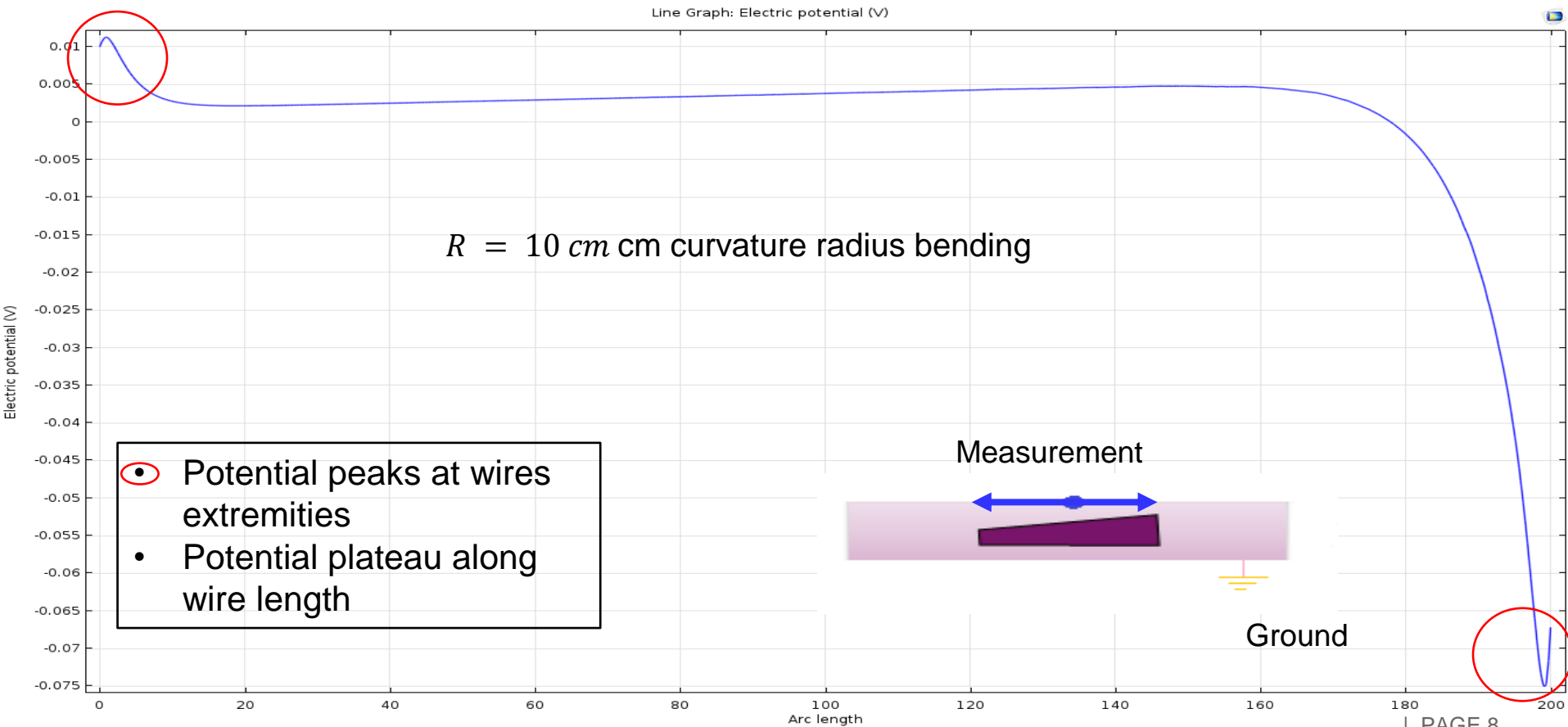
GaN wire as active material



- ✓ Embedded into dielectric layer: parylene
- ✓ Bending constraint :
10 *cm* curvature radius

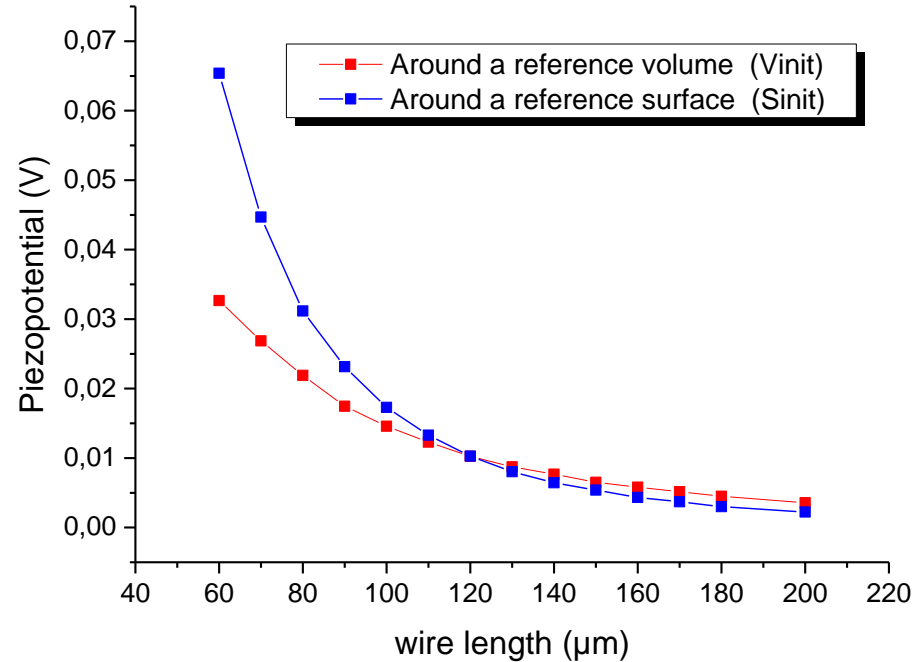
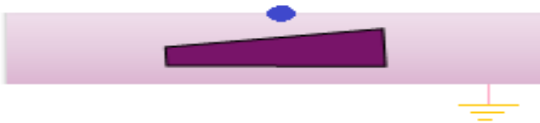


Understanding the potential generated by single wire



Effect of the length on the generated potential

- *Fixed:*
 - conicity angle $\alpha = 1^\circ$
- Parametric sweep around reference value :
 - Volume $V_{init} = 66 \mu m^3$
 - Surface $S_{init} = 330 \mu m^2$.
- Potential is measured at one point



- Shorter wires are preferred

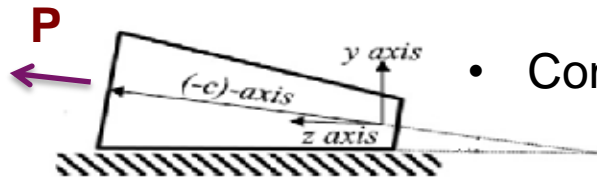
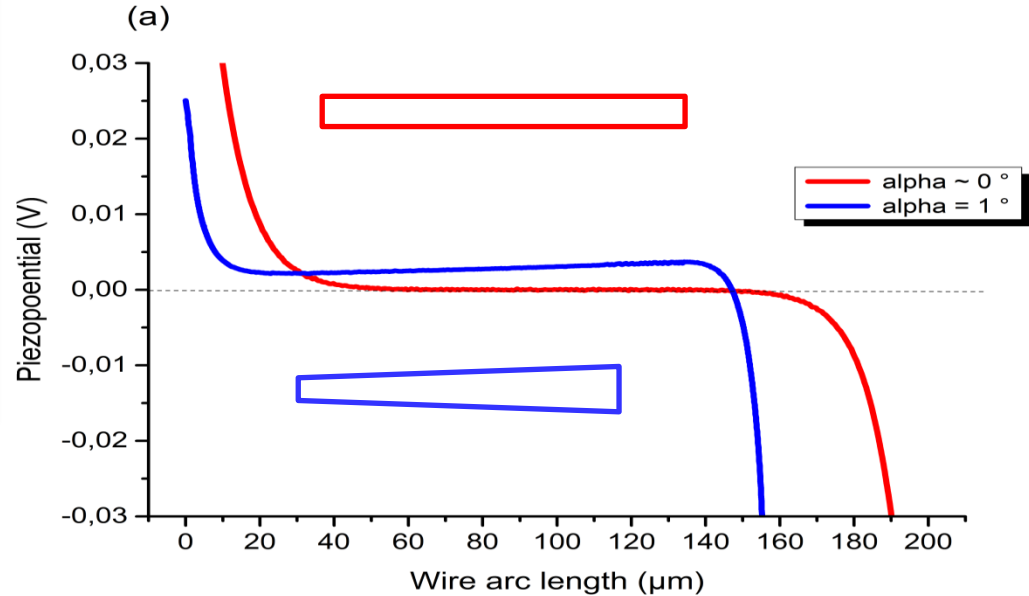
Conicity mandatory for potential generation

✓ *Fixed :*

- $\alpha = 0$ and 1°
- Top diameter $R_{top} = 700 \text{ nm}$
- curvature radius of deformation = 10 cm

✓ Potential is measured along the wire length

- Conicity mandatory for charge separation onto the wire facets.



- Condition: $P_y \neq 0$

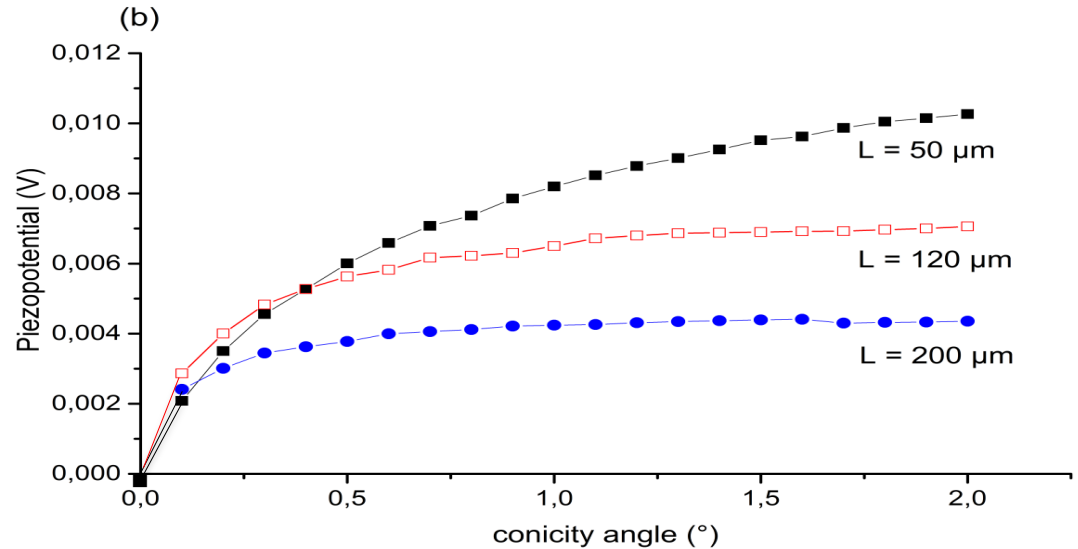
Effect of the conicity on the generated potential

✓ *Fixed:*

- Wire lengths : 50, 120, 200 μm
- Top diameter : $R_{top} = 700 \text{ nm}$

✓ Potential is measured at one point

Measurement



- Shorter wires are more sensitive to conicity variations.
- Larger conicity is not mandatory for potential generation.

Conclusion

- **COMSOL Simulation helped :**
 - Optimal wire geometry : L and α .
 - Insight about growth recipes improvements to reach optimal geometry.
- **Further works :** Compare different crystallographic shapes and orientations.
- **Open points :** Taking into account spontaneous polarization and dopant concentration (free carriers).

Thank you for your attention



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Etablissement public à caractère industriel et commercial | R.C.S Paris B 775 685 019

Conclusion

- Comsol has been used to :
 - Guide the design of the wire geometry :
 - Growth target : $120 \mu m$
 - Conicity of about 1°
- Further works : Compare different crystallographic shapes and orientations.
- Open points : Taking into account spontaneous polarization and dopant concentration (free carriers)

MOVPE growth technique: simplest solution



Sapphire substrate

- Substrate cleaning under H_2
- Substrate nitration under NH_3 : additional Al(O)N polar layer



SiNx layer deposition

- Simultaneous injection of Silane and NH_3 at high temperature.
- SiN_x layer as a mask for GaN nucleation.



Nucleation

- Injection of TMGa AND NH_3 precursors for short time to form nuclei.
- Relatively high V/III molar ratio.



Wire growth

- Injection of TMGa, NH_3 and silane under N_2 flux at high temperature ($1000^\circ C$).
- Low V/III molar ratio.

$$fv = \frac{R_{top}}{2 \cdot L \cdot \tan\left(\frac{\alpha}{2}\right) + R_{top}}$$

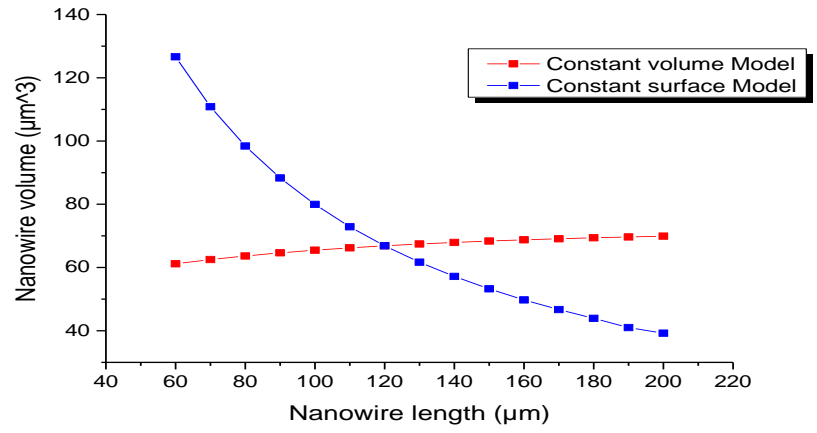
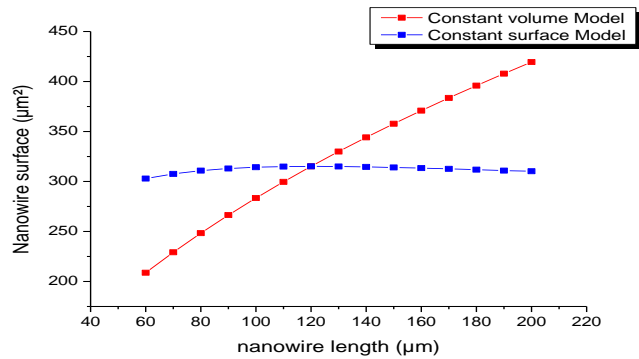
$$R_{top} = \frac{R_{top\,init}}{\sqrt{a}}$$

$$a = \frac{L}{L_{init}}$$

$$fs = \frac{R_{top}}{2 * L * \tan\left(\frac{\alpha}{2}\right) + R_{top}}$$

$$\text{with } R_{top} = \frac{R_{top\,init}}{a}$$

SURFACE AND VOLUME DURING SWEEP



$$6 * Surface_{facet} + surface_{top} + surface_{bottom}$$

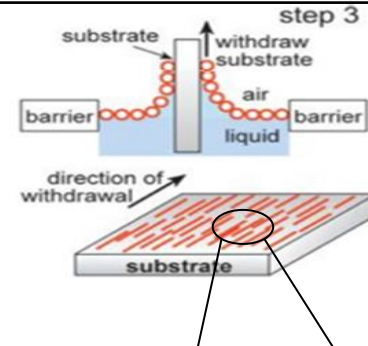
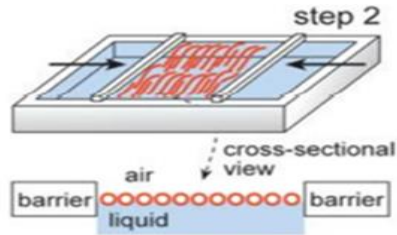
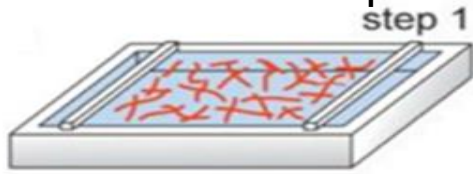
Tapez une équation ici.

Langmuir-Blodgett method

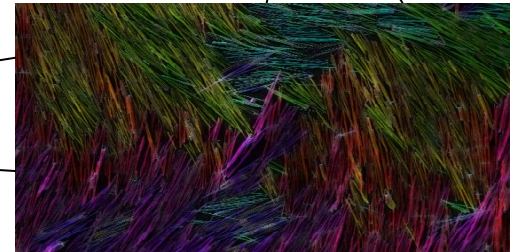
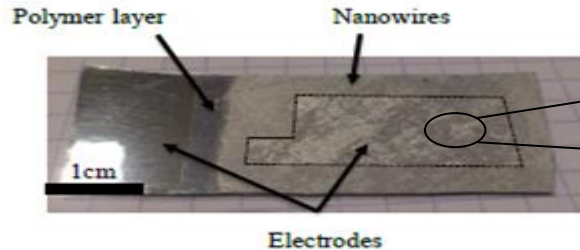
1. Pre-processing wire functionalization :

3 times 4 hours in incubation Isooctane and 2-propanol solution containing 1-octadecylamine diluted in hexane.

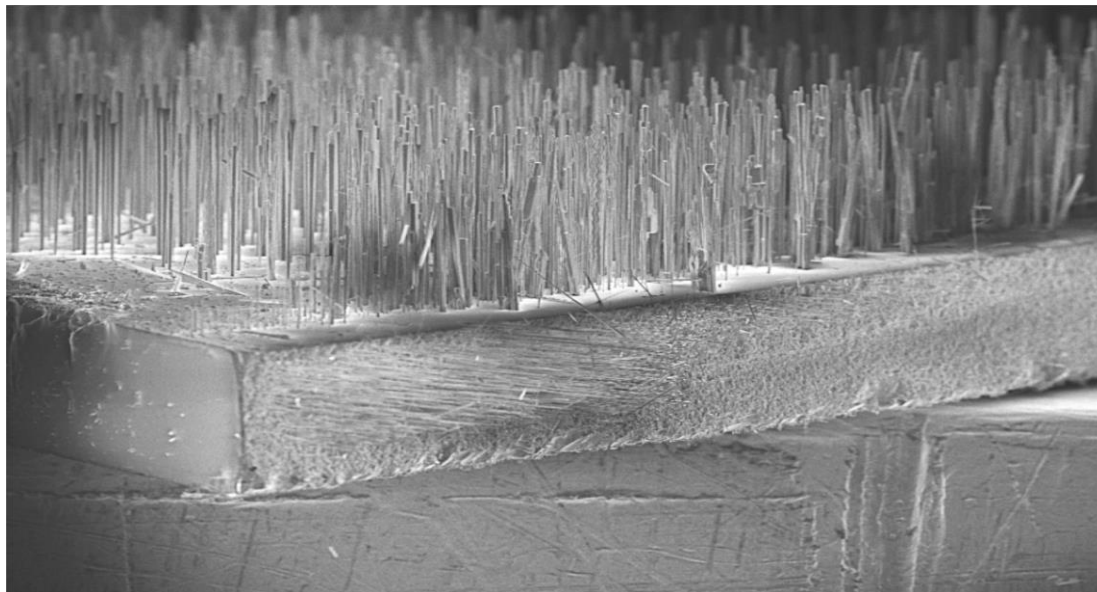
2. Process steps :



Final device



↑ Target orientation



Assembling the wires and device realization

■ Langmuir-Blodgett method

Iso-octane and 2-propanol
containing 1-octadecylamine in hexane .
12h incubation
Rinsed with IPA / isooctane solution

■ Capacitive structure

125 μm flexible polyethylene naphthalate (PEN) film
Evaporation of parylene-C under vacuum
Ti (20 nm) / Al (90 nm) electrodes

■ Device integration

0.5 mm plastic substrate covered
with an adhesive (holder)

